

TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

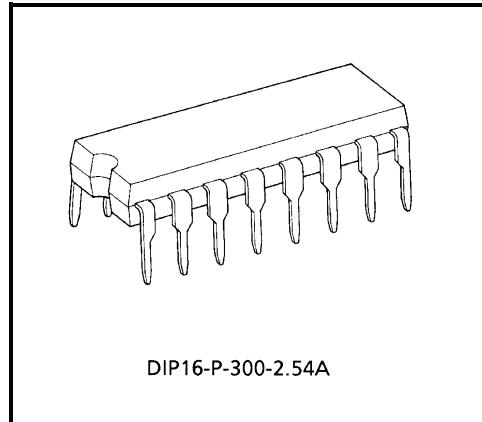
TD62707AP

4CH HIGH-VOLTAGE SOURCE DRIVER WITH ENABLE

The TD62707AP is comprised of four source current output stages and enable inputs which can gate the outputs. All outputs feature integral clamp diodes for switching inductive loads. Applications include relay, hammer and lamp drivers.

FEATURES

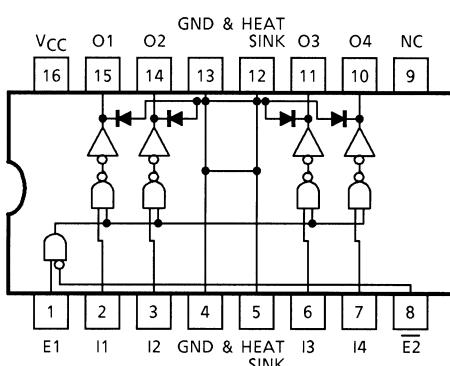
- High output voltage $V_{CC} - V_{OUT} = 50$ V MIN.
- Output current (single output) $I_{OUT} = -750$ mA MIN.
- Input compatible with TTL, 5 V CMOS
- Output clamp diodes
- Enable inputs E_1, \bar{E}_2
- GND terminal = HEAT SINK
- Package type : DIP-16 pin



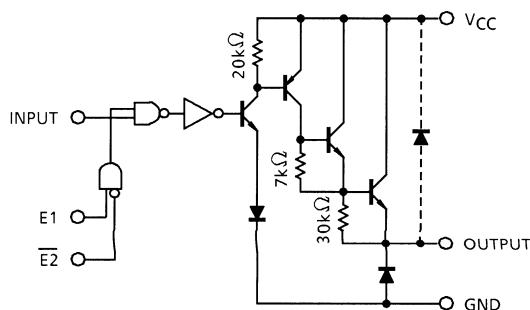
DIP16-P-300-2.54A

Weight: 1.11 g (Typ.)

PIN CONNECTION (TOP VIEW)



SCHEMATICS (EACH DRIVER)



Note: The output parasitic diodes cannot be used as clamp diodes.

TRUTH TABLE

E1	$\bar{E}2$	IN1~4	OUT1~4
H	H	H	OFF
H	L	H	ON
L	H	H	OFF
H	H	L	OFF
L	L	H	OFF
L	L	L	OFF
H	L	L	OFF

MAXIMUM RATINGS ($T_a = 25^\circ C$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Supply Voltage	V_{CC}	50	V
Output Voltage	V_{OUT}	-50	V
Output Current	I_{OUT}	-0.75	A / ch
Input Voltage	V_{IN1}	-0.5~15	V
	V_{IN2} (Note 1)	-0.5~ V_{CC}	
Clamp Diode Reverse Voltage	V_R	50	V
Clamp Diode Forward Current	I_F	-0.75	A
Power Dissipation	P_D	1.47 / 2.7 (Note 2)	W
Operating Temperature	T_{opr}	-40~85	°C
Storage Temperature	T_{stg}	-55~150	°C

Note 1: $V_{CC} \leq 15$ V

Note 2: On PCB (50 × 50 × 1.6 mm Cu 50%)

RECOMMENDED OPERATING CONDITIONS ($T_a = -40\sim85^\circ C$)

CHARACTERISTIC	SYMBOL	CONDITION	MIN	TYP.	MAX	UNIT
Supply Voltage	V_{CC}	—	—	—	50	V
Output Voltage	V_{OUT}	—	0	—	-50	V
Output Current	I_{OUT} (Note)	DC 1 Circuits, $T_a = 25^\circ C$	0	—	-600	mA / ch
		$T_{pw} = 25$ ms, 4 Circuits	0	—	-600	
		$T_a = 85^\circ C, T_j = 120^\circ C$	Duty = 10 %	0	—	
		Duty = 50 %	0	—	-160	
Input Voltage	V_{IN}	—	0	—	15	V
	$"H"$ level	V_{IH1} $V_{CC} > 15$ V	2.0	—	15	
		V_{IH2} $V_{CC} \leq 15$ V	2.0	—	V_{CC}	
	"L" level	V_{IL}	—	0	—	0.8
Clamp Diode Reverse Voltage	V_R	—	—	—	50	V
Clamp Diode Forward Current	I_F	—	—	—	600	mA
Power Dissipation	P_D	$T_a = 85^\circ C$	(Note)		—	1.2 W

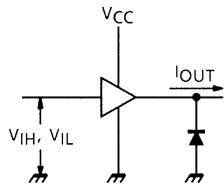
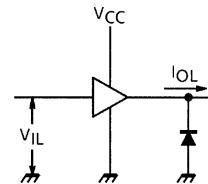
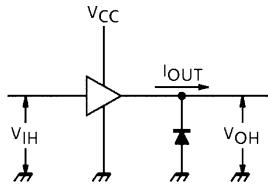
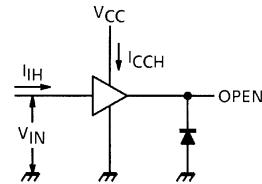
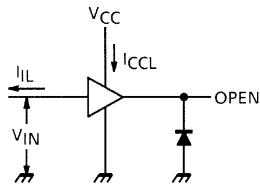
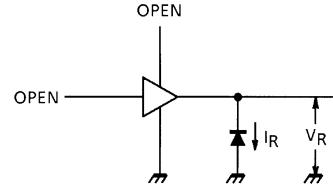
Note: On PCB (50 × 50 × 1.6 mm Cu 50%)

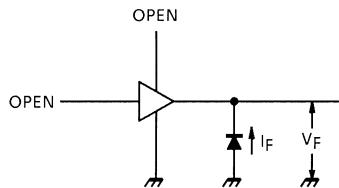
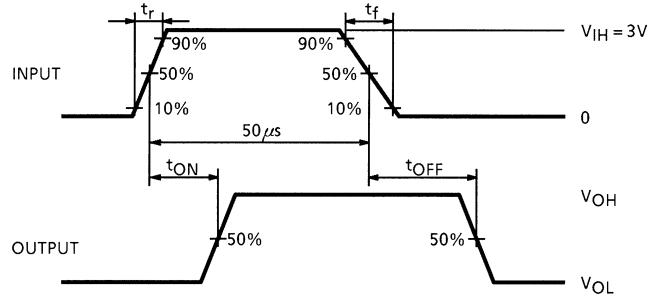
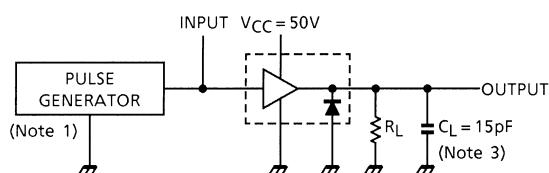
ELECTRICAL CHARACTERISTICS

(Ta = 25°C unless otherwise noted V_{CC} = 50 V, "H" = V_{IH}, "L" = V_{IL})

CHARACTERISTIC		SYMBOL	TEST CIR-CUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT	
Input Voltage	"H" level	V _{IH}	1	—	2.0	—	—	V	
	"L" level	V _{IL}			—	—	0.8		
Input Current	"H" level	IN	I _{IH}	V _{IN} = H V _{E1} = H V _{E2} = H	—	70	100	μA	
		E1			—	0	10		
		Ē2			—	66	100		
Input Current	"L" level	IN	I _{IL}	V _{IN} = L V _{E1} = L V _{E2} = H	—	-40	-100	μA	
		E1			—	-20	-50		
		Ē2			—	-40	-100		
Output Leakage Current		I _{OL}	2	V _{CC} = 50 V, OUTPUT OFF	—	—	100	μA	
Supply Current		I _{CCH}	4	V _{IN} = H, V _{E1} = H V _{E2} = L, OUTPUT OPEN	—	5.5	7.0	mA	
		I _{CCL}	5	V _{IN} = L, V _{E1} = H V _{E2} = L, OUTPUT OFF	—	5.5	7.0		
Output Voltage	"H" level	V _{OH}	3	V _{IN} = H, V _{E1} = "H" V _{E2} = L, I _{OUT} = -500 mA	V _{CC} -2.5	V _{CC} -2.0	—	V	
Clamp Diode Reverse Current		I _R	6	V _R = 50 V	—	—	100	μA	
Clamp Diode Forward Voltage		V _F	7	I _F = 500 mA	—	1.5	2.0	V	
Turn-On Delay		t _{ON}	8	V _{CCE} = 50 V, R _L = 83 Ω	—	0.5	—	μs	
Turn-Off Delay		t _{OFF}			—	6.0	—		

TEST CIRCUIT

1. V_{IH}, V_{IL}2. I_{OL}3. V_{OH}4. I_{IH}, I_{CCH}5. I_{IL}, I_{CCL}6. I_R

7. V_F 8. t_{ON} , t_{OFF} 

Note 1: Pulse Width 50 μ s, Duty Cycle 10%

Output Impedance 50 Ω , $t_r \leq 5$ ns, $t_f \leq 10$ ns

Note 2: $V_{IH} = 3$ V, $E_1 = V_{IH}$, $E_2 = GND$, $V_{CC} = 50$ V

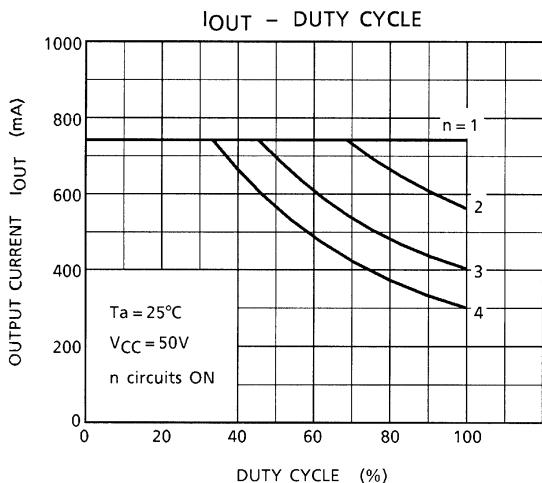
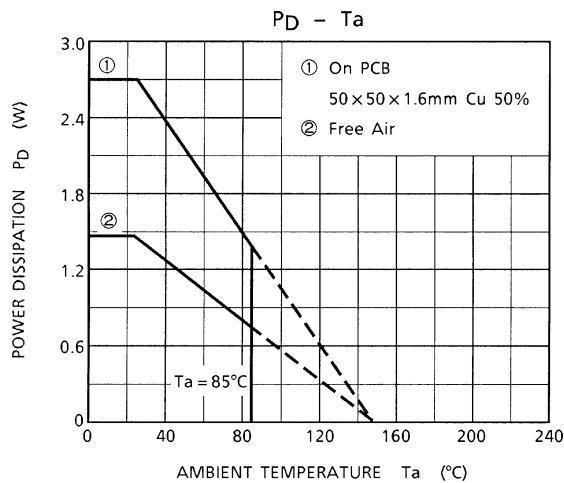
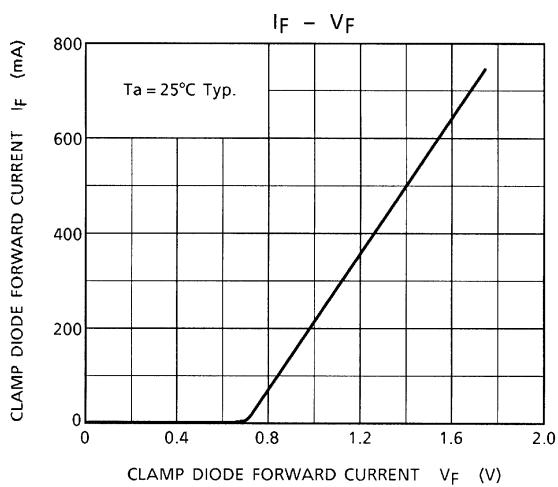
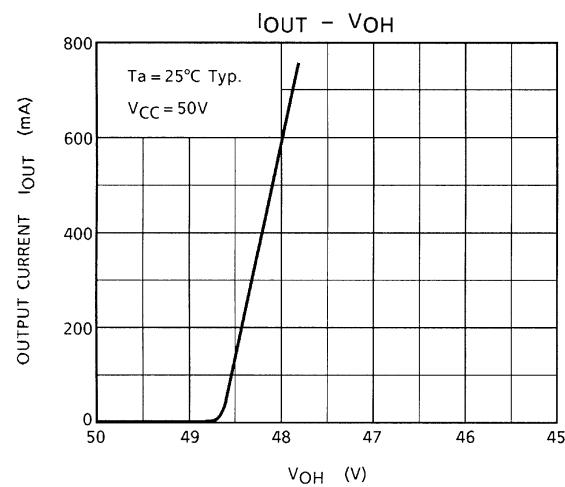
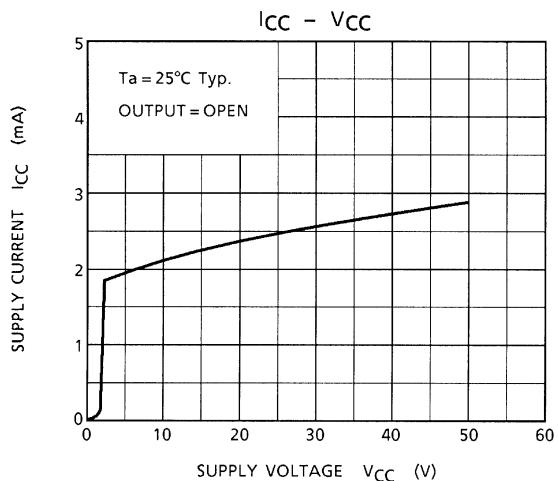
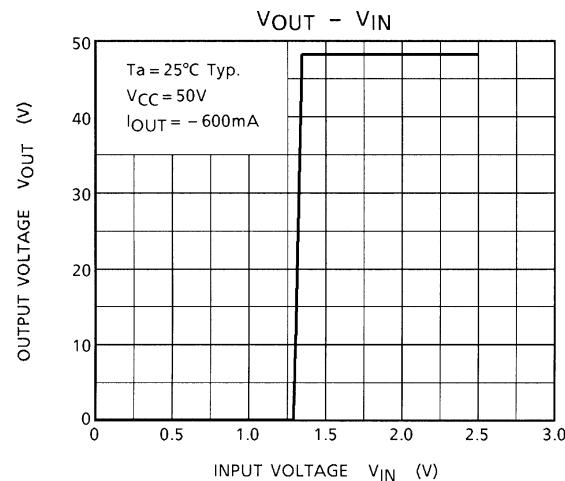
Note 3: C_L includes probe and jig capacitance

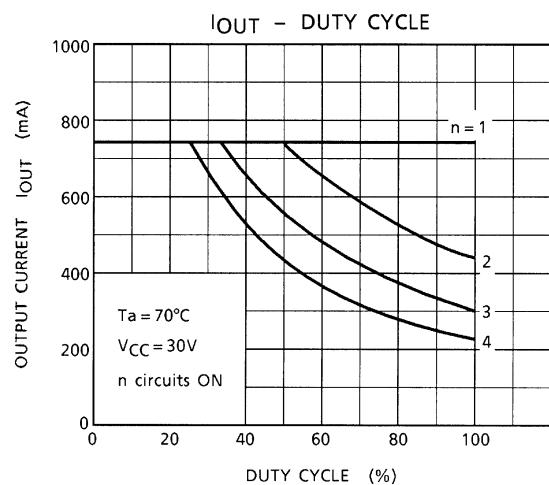
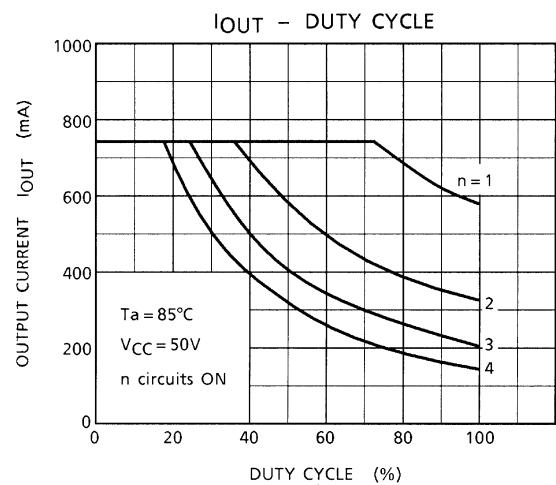
PRECAUTIONS for USING

This IC does not integrate protection circuits such as overcurrent and overvoltage protectors.

Thus, if excess current or voltage is applied to the IC, the IC may be damaged. Please design the IC so that excess current or voltage will not be applied to the IC.

Utmost care is necessary in the design of the output line, VCC and GND line since IC may be destroyed due to short-circuit between outputs, air contamination fault, or fault by improper grounding.

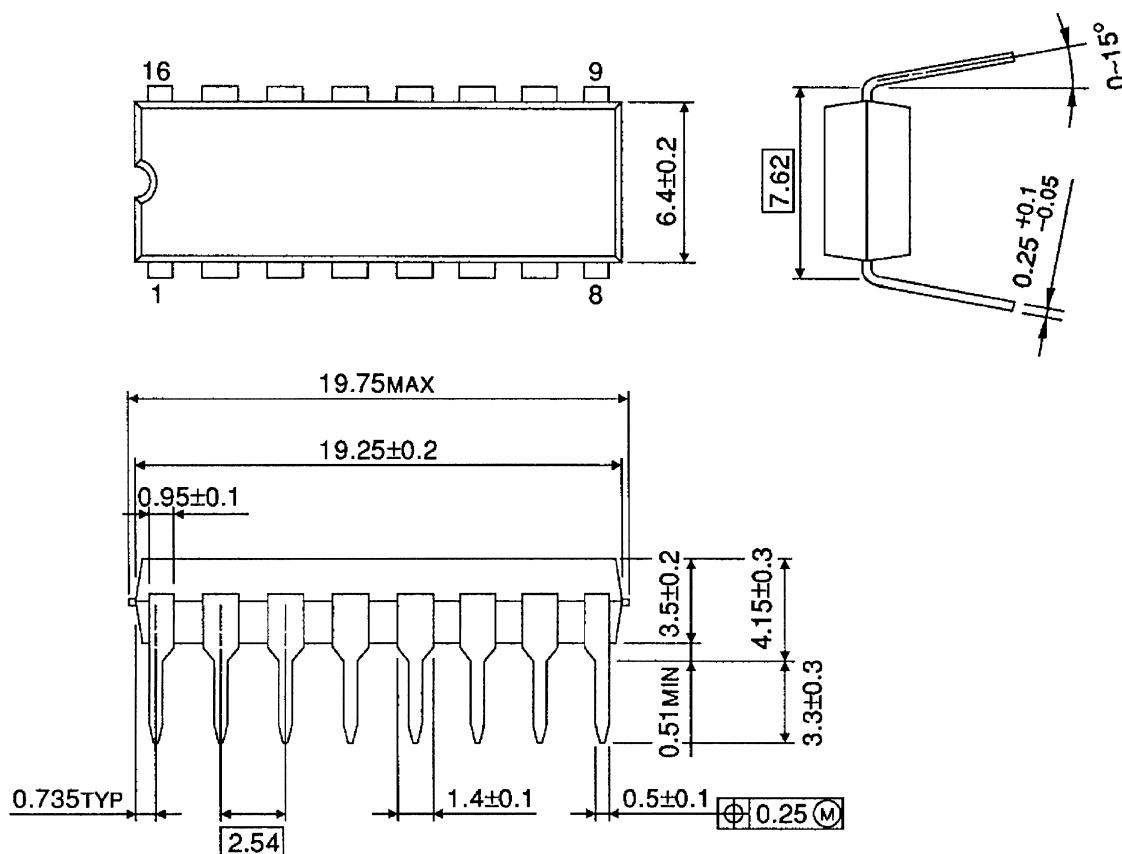




PACKAGE DIMENSIONS

DIP16-P-300-2.54A

Unit: mm



Weight: 1.11 g (Typ.)

RESTRICTIONS ON PRODUCT USE

000707EBA

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